Nom : mini plateforme chauffante.
Modèle: VB-215A
Temp. Plage : 160 ~ 250 ℃
N.W. : 90,4 g
Zone de travail : 20*18,5 mm
Taille du produit: 70,5x76,7x21,6 mm
Application : convient à 99 % des puces du marché, universel pour enlever la colle et l'étain de différents types d'iPhone, Huawei et autres processeurs de téléphones mobiles.

Type-C USB

Mini Heating Platform

160℃~250℃ Adjustable

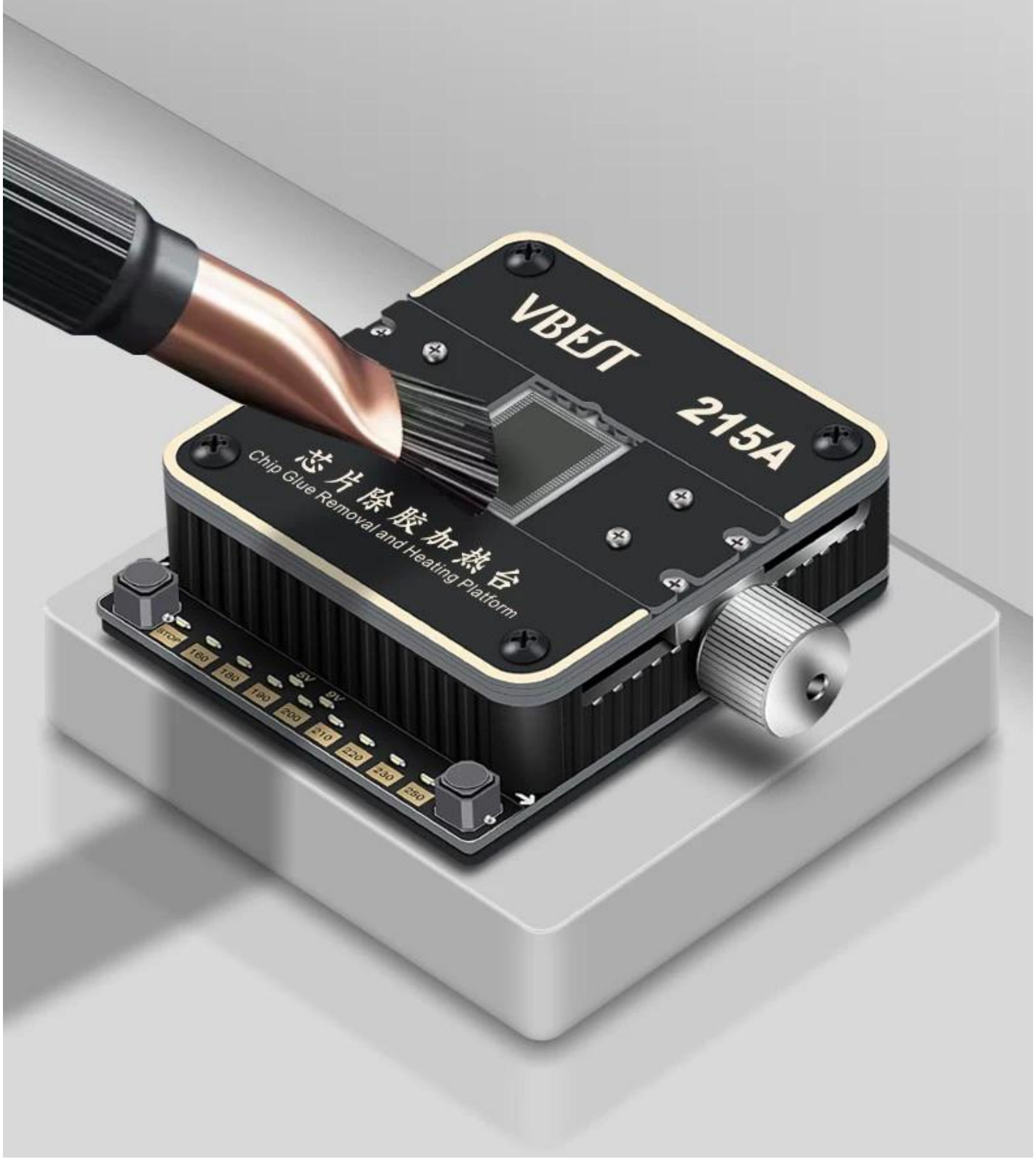
No need for heat gun or soldering iron heating, no need for soldering wick
No damage to solder pads and paint

No need for Soldering Wick

After heating to the set temperature, use a cotton swab to clean up the residual tin. No damage to the solder pad paint, no need for soldering wick wiping to wear out the chip

Heating to remove tin

Turn on the heating platform and heating to the preset temperature, you can use a brush or cotton swab to remove residual tin without soldering wick.
Gently wipe to remove tin and glue easily.



160℃~250℃

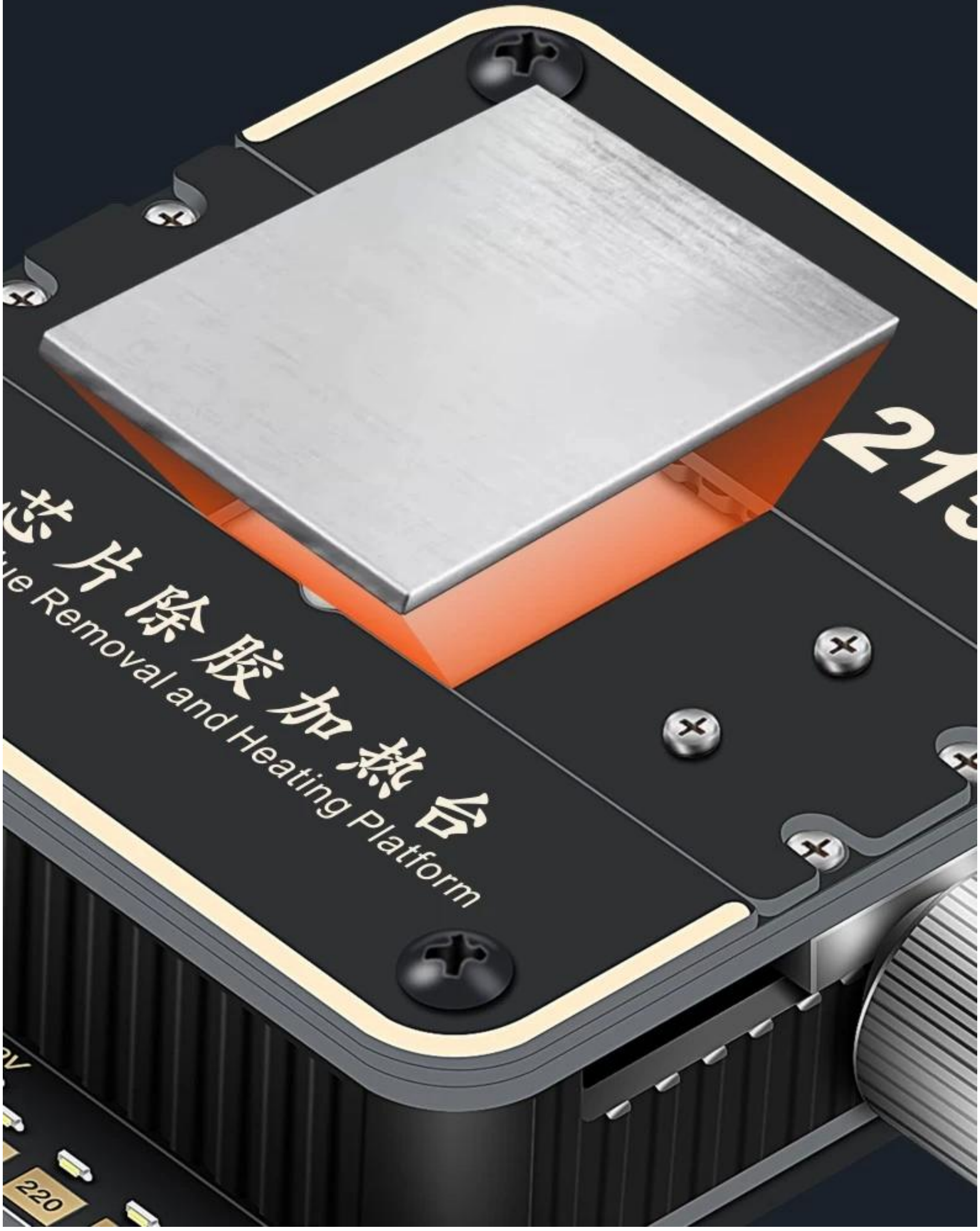
Constant Temperature Heating

During heating operation, the temperature can be adjusted between 160~250 ℃
Effectively prevent chip burnout caused by high temperature or improper adjustment

Low Voltage Heating Plate

Fast heating, no leakage, anti-static, safer heating

Built in professional tuning curve, no need to worry about chip damage caused by thermal stress



Flexible hidden screw rod

Hidden screw rod, flexible and clever, extendable
and fixed clamping the chips
Prevent residue from falling into the screw,
making it more durable

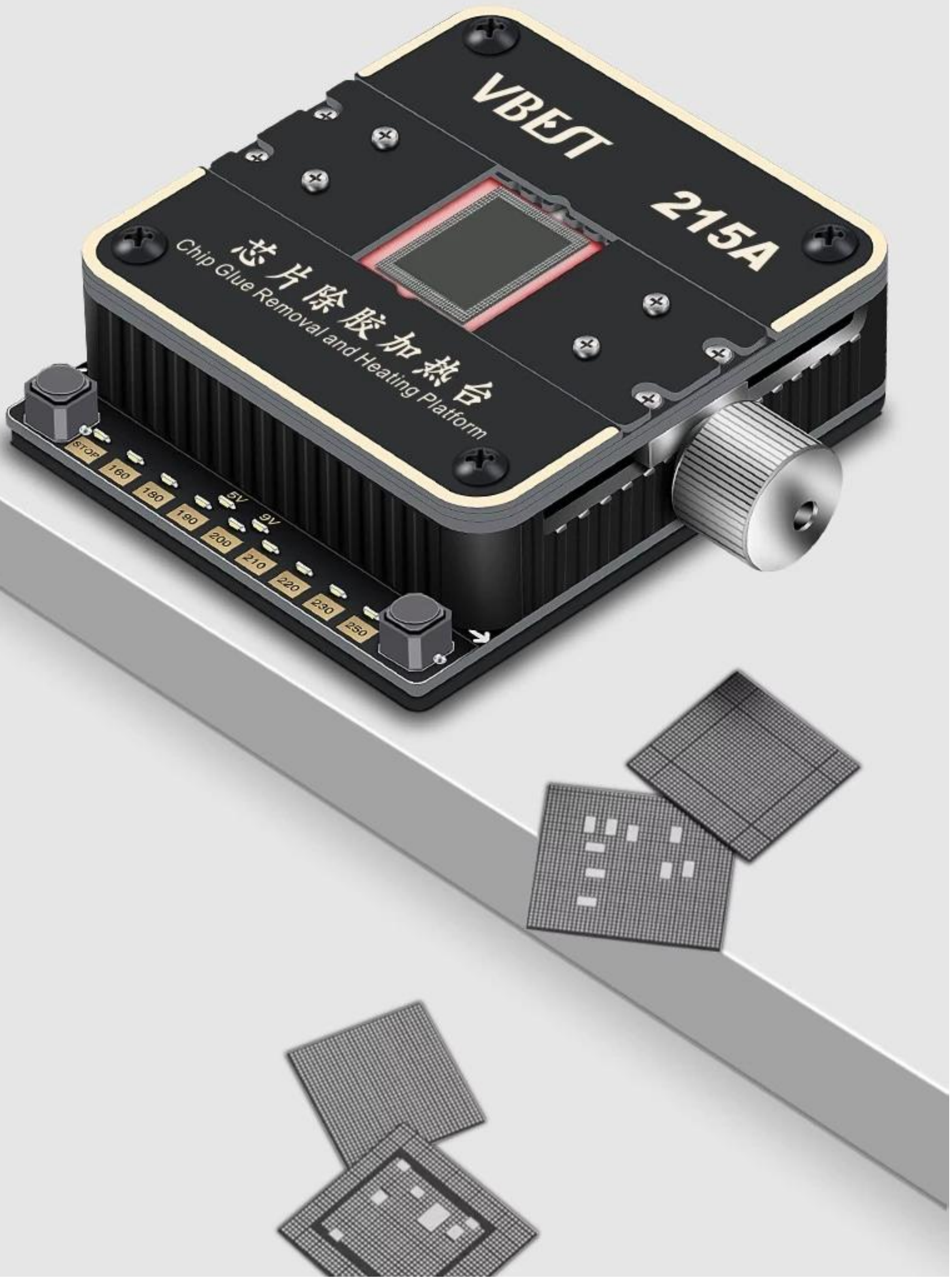
Uniform Heating

No need for heat gun heating, it is safer to scrape glue
at a temperature 100 ℃ lower than the heat gun
No need to repeatedly scrape with a soldering iron,
no damage to the solder pads

Temperature adjustable 160~250℃

Suitable for 99% of chips

Work area: 20mm×18.5mm (Max)
Support multi generation iPh, Huawei phone CPU chips
and hard drives



Parameter

Name	Model	Temp. Range
Mini Heating Platform	VB-215A	160~250℃
N. W.	**Work area**	**Product Size**
90.4g	20×18.5mm	70.5×76.7×21.6mm

Application Suitable for 99% of chips on the market, universal for removing glue and tin from various types of iPhones, Huawei and other mobile phone CPU

* The above dimensions are measured manually and may have about 1-2mm error